



Product Change Notification

Change Notification #: 117471 - 00
Change Title: Hot Swap Backplane Improvement
A2U8X35S3HSDK1,
PCN 117471-00, Product Design,
Firmware update
Date of Publication: March 9, 2020

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	March 23, 2020
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41 of the Intel Server Hot-Swap Backplanes listed in the "Products Affected" table below. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
A2U8X35S3HSDK1	958246	J56722-002	G97160-371	J56722-003	G97160-372

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 9, 2020	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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